03-16-2004

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To the Director of the United States Patent and Trademark Office	
Name of conveying party(ies): Ryuta TAKI	2. Name and address of receiving party(ies):
Ryuta IAKI	Name: Sony Corporation
	Address: 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan
Additional name(s) of conveying party(ies) attached? Yes	· _ · _ · _ · _ ·
3. Nature of Conveyance:	
■ Assignment	
☐ Security Agreement ☐ Change of Name	
☐ Other Execution Date: July 14, 2003	Additional name(s) and address(es) attached? ☐ Yes
4. Application number(s) or patent number(s):	
If this document is being filed together with a new application, th	e execution date of the application is:
A. Patent Application No.(s)	B. Patent No.(s)
10/469,703	
Additional numbers atta	l ached? □ Yes ■ No
5. Name and address of party to whom correspondence	
concerning document should be mailed:	6. Total applications and patents involved: 1
Contain North or	7. Total fee (37 CFR 3.41): \$40.00
Customer Number	■ Enclosed
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Tel. (703) 413-3000 Fax. (703) 413-2220	8. Deposit account number: 15-0030 (Attach duplicate copy of this page if paying by deposit account)
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9. Statement and signature	
To the best of my knowledge and belief, the foregoing information	tion is true and correct and any attached copy is a true
copy of the original document.	Scaletta & March 11, 2004
Bradley D. Lytle Name of Person Signing S	jonature Date
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10,469,	703
	S03P0049US00

Docket 1	Number:
ASSIGNMENT	
WHEREAS, I, as a below named inventor, residing at the address stated next to my name only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and us CONTENT DISTRIBUTION SYSTEM	
for which application for Letters Patent of the United States of America was executed by me on the date in	dicated next to my name
and address;	
AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 I Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to said application disclosing the invention and in, to and under any Letters Patent or similar legal protection therefor in the United States and in any and all foreign countries;	and under said invention
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good are the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated bethereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, interest in the said invention, said application, including any divisions and continuations thereof, and in a Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in a rights and/or convention rights under the International Convention for the Protection of Industrial Property, Interesting to Patents, Designs and Industrial Models, and any other international agreements to which the Ladheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents in the United States and countries foreign thereto, and I hereby authorize and request the Commission said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest to	ow, by these presents do the entire right, title and and to any and all Letters and to any and all priority fer-American Convention United States of America or patents or securing of ther of Patents to issue the
And I further agree to execute all necessary or desirable and lawful future documents, including ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from tin and without further remuneration, in order to perfect title in said invention, modifications, and improve applications and Letters Patent of the United States and countries foreign thereto;	ne-to-time present to me
And I further agree to properly execute and deliver and without further remuneration, such necessar papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof st prepare at its own expense;	obtaining any reissue or
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertine relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries accessible to me and will testify as to the same in any interference or litigation related thereto;	
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made would conflict with this assignment and sale.	de or entered into which
And I hereby authorize and request my attorney(s) of record in this application to insert the serial n this application in the spaces that follow: Serial Number: 10/469,703 Filing Date: September 10/469,703 Filing Date: September 10/469,703	umber and filing date of per 12, 2003
This assignment executed on the dates indicated below.	
RYUTA TAKI 14, Jul.	, 2003
	U.S. Patent Application
KANAGAWA, JAPAN	

Residence of first or sole inventor
Ryutu Taki

Signature of first or sole inventor

RECORDED: 03/11/2004

PATENT REEL: 015069 FRAME: 0446

14, Jul. 2003

Date of this assignment